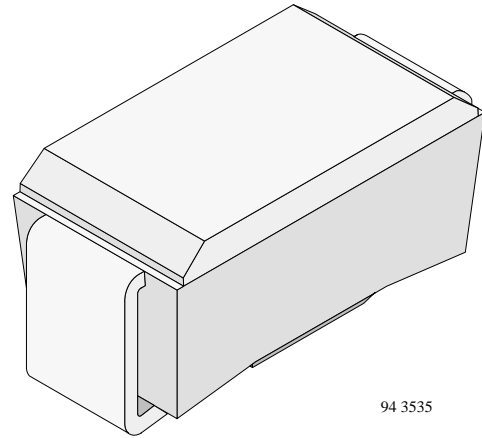


Schottky Barrier Rectifier

Features

- High efficiency
- Low power losses
- Very low switching losses
- Low reverse current
- High surge capability



94 3535

Applications

Polarity protection
Low voltage, high frequency rectifiers

Absolute Maximum Ratings

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Type	Symbol	Value	Unit
Repetitive peak reverse voltage			V_{RRM}	90	V
Reverse voltage			V_R	90	V
Peak forward surge current	$t_p=10\text{ms}$, half sinewave		I_{FSM}	30	A
Average forward current			I_{FAV}	1.5	A
Junction temperature			T_j	150	$^\circ\text{C}$
Storage temperature range			T_{stg}	-55...+150	$^\circ\text{C}$

Maximum Thermal Resistance

$T_j = 25^\circ\text{C}$

Parameter	Test Conditions	Symbol	Value	Unit
Junction lead	$T_L=\text{constant}$	R_{thJL}	25	K/W
Junction ambient	mounted on epoxy-glass hard issue, Fig. 1a	R_{thJA}	150	K/W
	mounted on epoxy-glass hard issue, Fig. 1b	R_{thJA}	125	K/W
	mounted on Al-oxid-ceramic (Al_2O_3), Fig. 1b	R_{thJA}	100	K/W

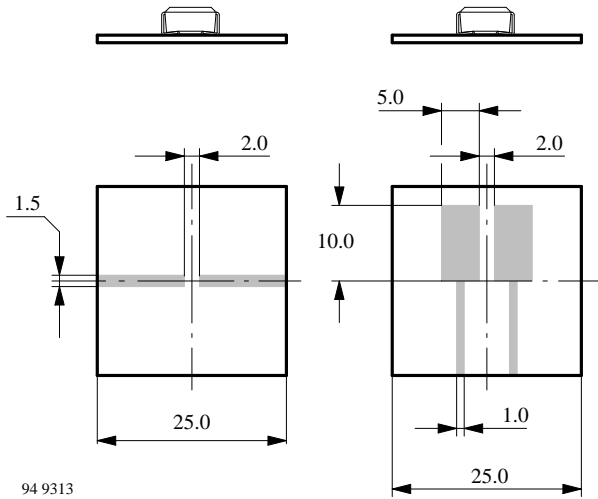
BYS12-90

Characteristics

$T_j = 25^\circ\text{C}$

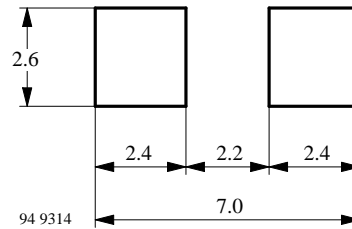
Parameter	Test Conditions	Type	Symbol	Min	Typ	Max	Unit
Forward voltage	$I_F=1\text{A}$		V_F			900	mV
	$I_F=15\text{mA}$		V_F			360	mV
Reverse current	$V_R=V_{RRM}$		I_R			200	μA
	$V_R=V_{RRM}, T_j=100^\circ\text{C}$		I_R			2	mA

Typical Characteristics ($T_j = 25^\circ\text{C}$ unless otherwise specified)



94 9313

Figure 1 : Boards for R_{thJA} definition (copper overlay 35μ)



94 9314

Figure 2 : Recommended foot pads

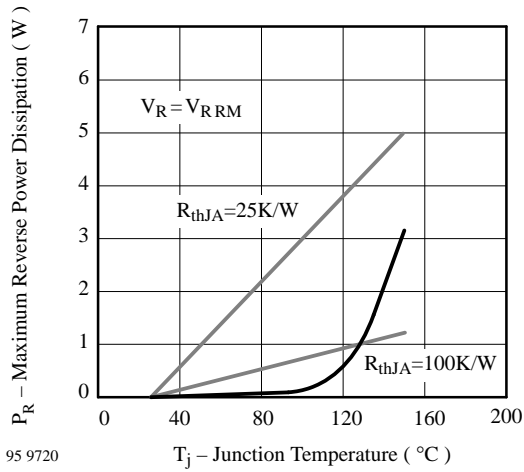


Figure 3 : Maximum Reverse Power Dissipation vs. Junction Temperature

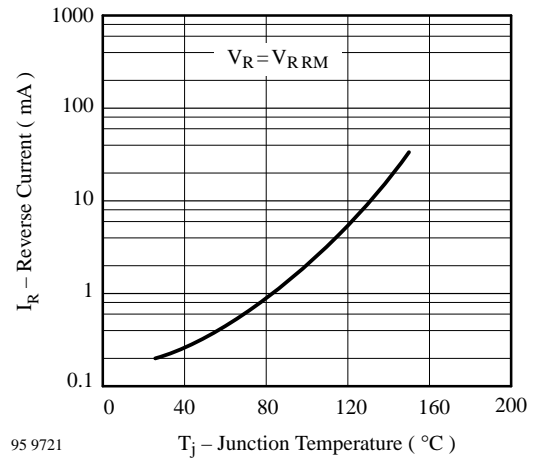


Figure 4 : Reverse Current vs. Junction Temperature

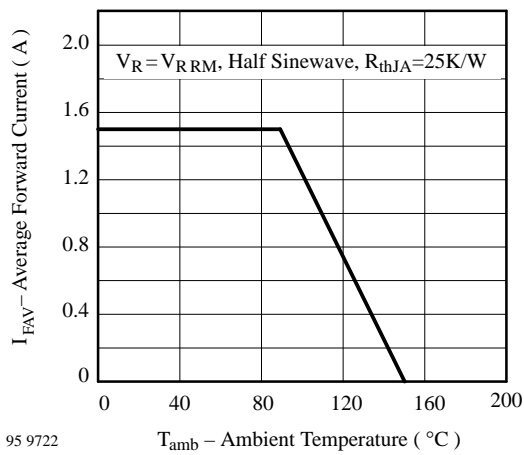


Figure 5 : Average Forward Current vs. Ambient Temperature

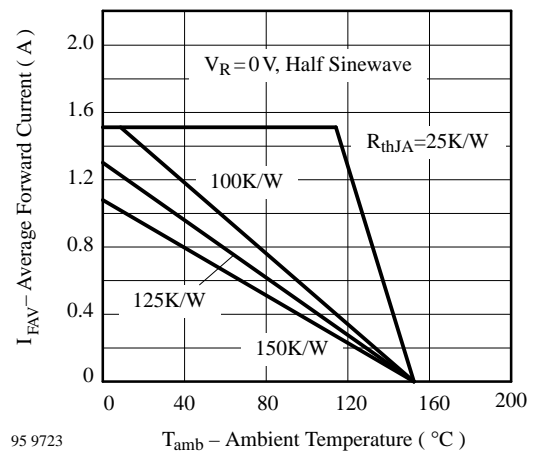


Figure 6 : Average Forward Current vs. Ambient Temperature

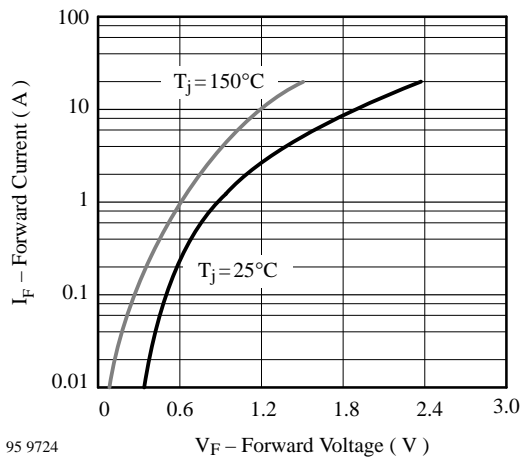
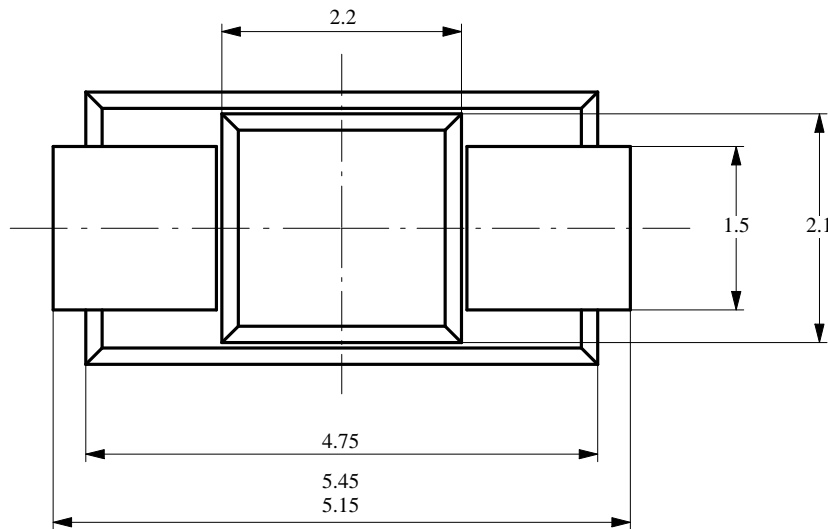


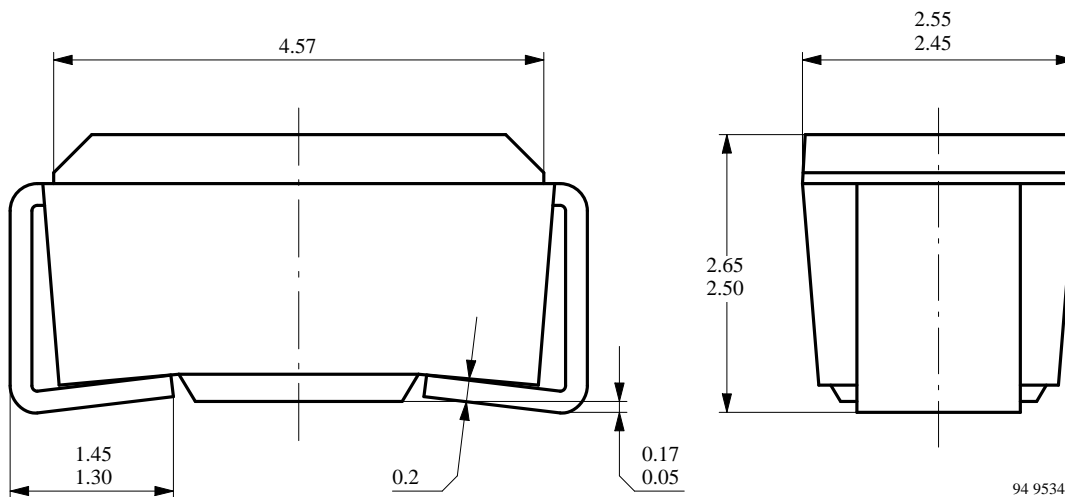
Figure 7 : Forward Current vs. Forward Voltage

Dimensions in mm



Plastic Case
JEDEC DO 214 AC
SOD 106 A

Cathode indicated by a Band



94 9534

OZONE DEPLETING SUBSTANCES POLICY STATEMENT

It is the policy of **TEMIC TELEFUNKEN microelectronic GmbH** to

1. Meet all present and future national and international statutory requirements and
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

Of particular concern is the control or elimination of releases into the atmosphere of those substances which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) will soon severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

TEMIC TELEFUNKEN microelectronic GmbH semiconductor division has been able to use its policy of continuous improvements to eliminate the use of any ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA and
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

TEMIC can certify that our semiconductors are not manufactured with and do not contain ozone depleting substances.

We reserve the right to make changes to improve technical design without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use TEMIC products for any unintended or unauthorized application, the buyer shall indemnify TEMIC against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

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